#### SCOPE:

This specification applies to the Pb Free high current type SMD inductors for MSCDRI-6012X-SERIES

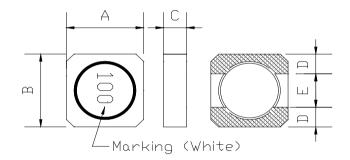
Warn:It is here not to use synchronous rectification circuit!

#### **PRODUCT INDENTIFICATION**

#### MSCDRI - 6012X - 100 M

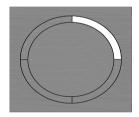
- 1
- 2
- 3 4
- ① Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code

#### (1) SHAPES AND DIMENSIONS



A: 6.0±0.2 mm
B: 6.0±0.2 mm
C: 1.2 Max. mm
D: 2.0 Typ. mm
E: 2.0 Typ. mm

#### **Void Appearance Tolerance Limit**



- 1. The length of the hole in the epoxy of the sealed glue position should be less than 1/4 of the DR core 's circumference, otherwise, it is NG.
- 2. The total length of the amount of hole in the epoxy should be less than 1/4 of the DR core 's circumference, otherwise, it is NG.

# (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

**TEST INSTRUMENTS** 

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)



### **TABLE 1**

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current		Moulsing
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)Max.	IDC1(A)	IDC2(A)	Marking
MSCDRI-6012X-2R2	2.2	N	100kHz/0.1V	70m	2.30	2.30	2R2
MSCDRI-6012X-2R5	2.5	N	100kHz/0.1V	70m	2.30	2.30	2R5
MSCDRI-6012X-3R0□	3.0	N	100kHz/0.1V	81m	2.00	2.00	3R0
MSCDRI-6012X-3R3	3.3	N	100kHz/0.1V	90m	1.90	1.90	3R3
MSCDRI-6012X-3R9	3.9	N	100kHz/0.1V	0.100	1.70	1.70	3R9
MSCDRI-6012X-4R7□	4.7	M,N	100kHz/0.1V	0.130	1.60	1.50	4R7
MSCDRI-6012X-5R6□	5.6	M,N	100kHz/0.1V	0.145	1.50	1.40	5R6
MSCDRI-6012X-6R8	6.8	M,N	100kHz/0.1V	0.165	1.40	1.30	6R8
MSCDRI-6012X-8R2	8.2	M,N	100kHz/0.1V	0.200	1.20	1.20	8R2
MSCDRI-6012X-100□	10	M,N	100kHz/0.1V	0.240	1.00	1.00	100

%  $\square$  specify the inductance tolerance , M(±20%) , N(±30%)

※ IDC1: Based on inductance change (△L/Lo: drop 30% Max.) @ ambient temp. 25°C

IDC2: Based on temperature rise ( $\triangle T$ : 40°C TYP.)

Rated DC Current: The less value which is IDC1 or IDC2.



# (4) RELIABILITY TEST METHOD MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damage.	Л			
		R5 45±2 45±2 10 20 R340			
		PRESSURE ROD figure-1			
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		and when a vibration having an amplitude of 1.52mm			
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
	damage.	(A total of 6 hours)			
Caldavahility	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
Solderability	More than 90%	over the whole of the sample before hard, the sample shall			
		then be preheated for about 2 minutes in a temperature of			
		130∼150℃ and after it has been immersed to a depth 0.5mm			
		below for 3±0.2 seconds fully in molten solder M705 with			
		a temperature of 245±5℃.			
		More than 90% of the electrode sections shall be couered			
		with new solder smoothly when the sample is taken out of			
		the solder bath.			



### **MECHANICAL**

TEST ITEM		SPECIFICATION						
Resistance to	There shall be	Temperature profile of reflow soldering						
Soldering heat	no damage or							
(reflow soldering)	problems.	Slow cooling (Stored at room temperature)  The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time.  The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.						

## **ELECTRICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS			
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in			
characteristics	0~2000 ppm/°C	an ambient temperature of -20 to +85℃,and the value			
		calculated based on the value applicable in a normal			
		temperature and narmal humidity shall be △L/L20°C ≦±10%.			



## **ENVIROMENT CHARACTERISTICS**

TEST ITEM				SPECIFICATION				
High temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmospere with						
storage		a tempera	a temperature of 125 $^{\circ}$ C and a normal humidity.					
	There shall be	Upon cor	Upon completion of the measurement shall be made after the					
	no mechanical	sample h	sample has been left in a normal temperature and normal					
	damage.	humidity	humidity for 1 hour.					
Low temperature	∆L/Lo≦±5%	The samp	The sample shall be left for 96±4 hours in an atmosphere with					
storage		a tempera	a temperature of -25±3℃.					
	There shall be	Upon completion of the test, the measurement shall be made						
	no mechanical	after the	after the sample has been left in a normal temperature and					
	damage.	normal h	normal humidity for 1 hour.					
Change of	∆L/Lo≦±5%	The samp	The sample shall be subject to 5 continuos cycles, such as shown					
temperature		in the tab	in the table 2 below and then it shall be subjected to standard					
	There shall be	atmosphe	eric (	conditions for 1 hour, af	ter which measureme	ent		
	no other dama-	shall be r	shall be made.					
	ge of problems							
				table 2				
				Temperature	Duration			
			1	–25±3℃	30 min.			
			•	(Themostat No.1)				
			2	Standard	No.1→No.2			
			_	atmospheric				
			3	85±2℃	30 min.			
				(Themostat No.2)				
			4	Standard	No.2→No.1			
			•	atmospheric	NO.2→NO.1			
Moisture storage	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in a temperature of						
		40±2℃ and a humidity(RH) of 90∼95%.						
	There shall be	Upon cor	Upon completion of the test, the measurement shall be made					
	no mechanical	after the	after the sample has been left in a normal temperature and					
	damage.	normal h	normal humidity more than 1 hour.					
Test conditions :								
The	sample shall be refle	w soldered	onto	the printed circuit boar	d in every test			

The sample shall be reflow soldered onto the printed circuit board in every test.



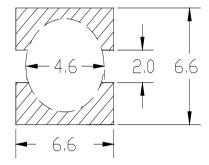
# (5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

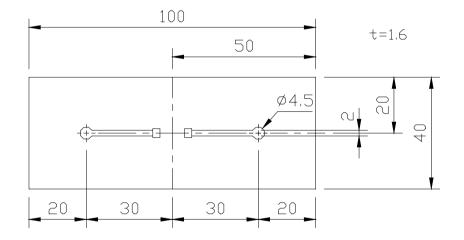
# (5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN)

Unit:mm



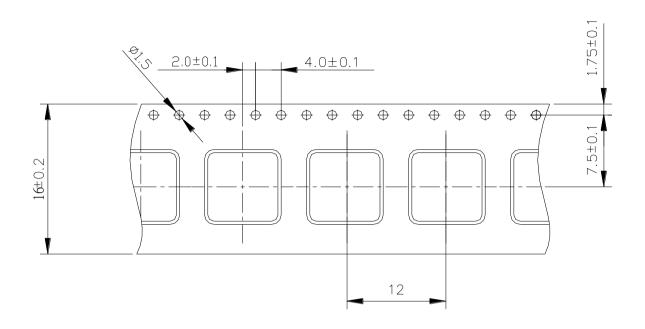
# (5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD



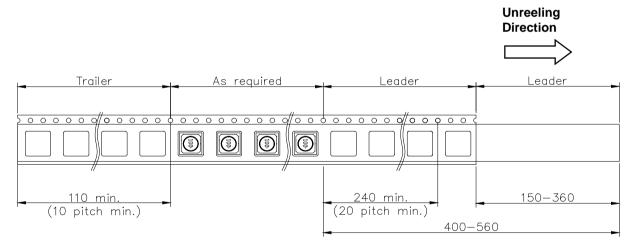


# (6) PACKAGING

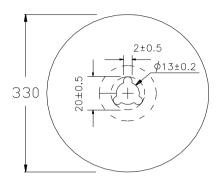
# (6)-1 CARRIER TAPE DIMENSIONS (mm)

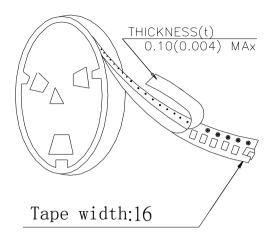


# (6)-2 TAPING DIMENSIONS (mm)



# (6)-3 REEL DIMENSIONS (mm)





# (6)-4 QUANTITY

3000pcs/Reel

The products are packaged so that no damage will be sustained.

